MC100EPT23

3.3V Dual Differential LVPECL to LVTTL Translator

The MC100EPT23 is a dual differential LVPECL to LVTTL translator. Because LVPECL (Positive ECL) levels are used, only +3.3 V and ground are required. The small outline 8-lead package and the dual gate design of the EPT23 makes it ideal for applications which require the translation of a clock and a data signal.

The EPT23 is available in only the ECL 100K standard. Since there are no LVPECL outputs or an external V_{BB} reference, the EPT23 does not require both ECL standard versions. The LVPECL inputs are differential. Therefore, the MC100EPT23 can accept any standard differential LVPECL input referenced from a V_{CC} of +3.3 V.

- 1.5 ns Typical Propagation Delay
- Maximum Operating Frequency > 275 MHz
- 24 mA LVTTL Outputs
- Operating Range: V_{CC} = 3.0 V to 3.6 V with GND = 0 V
- Open Input Default State
- Q Output Will Default LOW with Inputs Open or at GND

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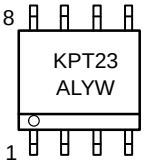
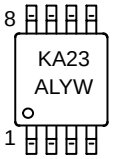
MARKING DIAGRAMS*

SO–8
D SUFFIX
CASE 751



TSSOP–8
DT SUFFIX
CASE 948R

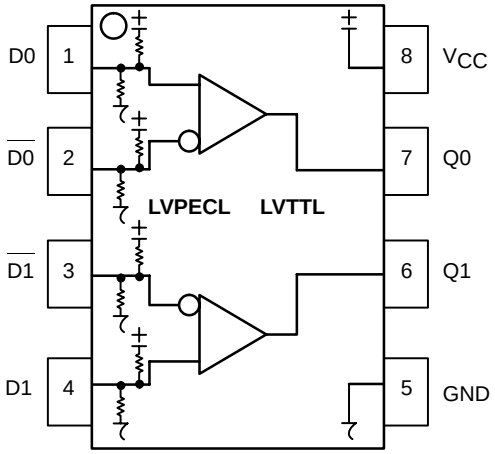


A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

*For additional information, see Application Note AND8002/D

ORDERING INFORMATION

Device	Package	Shipping
MC100EPT23D	SO–8	98 Units/Rail
MC100EPT23DR2	SO–8	2500 Tape & Reel
MC100EPT23DT	TSSOP–8	100 Units/Rail
MC100EPT23DTR2	TSSOP–8	2500 Tape & Reel



PIN DESCRIPTION

PIN	FUNCTION
Q0, Q1	LVTTL Outputs
D0**, D1** D0**, D1**	Differential LVPECL Inputs
V_{CC}	Positive Supply
GND	Ground

** Pins will default to $V_{CC}/2$ when left open.

Figure 1. 8–Lead Pinout (Top View) **and Logic Diagram**

ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor	75 kΩ
Internal Input Pullup Resistor	37.5 kΩ
ESD Protection Human Body Model Machine Model Charged Device Model	> 1.2 kV > 150 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Level 1
Flammability Rating Oxygen Index	UL–94 code V–0 A 1/8” 28 to 34
Transistor Count	91 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V_{CC}	Power Supply	GND = 0 V		3.8	V
V_I	Input Voltage	GND = 0 V	$V_I \leq V_{CC}$	3.8	V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
TA	Operating Temperature Range			–40 to +85	°C
T_{stg}	Storage Temperature Range			–65 to +150	°C
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction to Case)	std bd	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction to Case)	std bd	8 TSSOP	41 to 44	°C/W
T_{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

2. Maximum Ratings are those values beyond which device damage may occur.

PECL DC CHARACTERISTICS V_{CC} = 3.3 V, GND = 0 V (Note 3)

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{CCH}	Power Supply Current (Outputs set to HIGH)	10	18	25	10	18	25	10	18	25	mA
I_{CCL}	Power Supply Current (Outputs set to LOW)	15	26	33	15	26	33	15	26	33	mA
V_{IH}	Input HIGH Voltage	2075		2420	2075		2420	2075		2420	mV
V_{IL}	Input LOW Voltage	1355		1675	1355		1675	1355		1675	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Note 4)	2.0		3.3	2.0		3.3	2.0		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current D D	 –150		0.5	 –150		0.5	 –150		0.5	μA

NOTE: Circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

3. All values vary 1:1 with V_{CC}.
4. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

TTL DC CHARACTERISTICS V_{CC} = 3.3 V, GND = 0.0 V, T_A = –40°C to 85°C

Symbol	Characteristic	Condition	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage (Note 5)	I_{OH} = –3.0 mA	2.4			V
V_{OL}	Output LOW Voltage (Note 5)	I_{OL} = 24 mA			0.5	V
I_{OS}	Output Short Circuit Current		–180		–50	mA

NOTE: Circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

5. All loading with 500 ohms to GND.

AC CHARACTERISTICS V_{CC} = 3.0 V to 3.6 V, GND = 0.0 V (Note 6)

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Frequency (See Figure 2. F_{max}/JITTER)	275	350		275	350		275	350		MHz
t_{PLH}, t_{PHL}	Propagation Delay to C_L = 20 pF Output Differential (Note 7)	1.2 1.2	1.5 1.5	1.8 1.8	1.2 1.2	1.5 1.5	1.8 1.8	1.3 1.2	1.7 1.5	2.2 1.8	ns
t_{SK++} t_{SK--} t_{SKPP}	Output–to–Output Skew++ Output–to–Output Skew– – Part–to–Part Skew (Note 8)			60 25 500			60 25 500			60 25 500	ps
t_{JITTER}	Cycle–to–Cycle Jitter (See Figure 2. F_{max}/JITTER)		0.2	< 1		0.2	< 1		0.2	< 1	ps
V_{PP}	Input Voltage Swing (Differential)	150	800	1200	150	800	1200	150	800	1200	mV
t_r t_f	Output Rise/Fall Times C_L = 20 pF (0.8V – 2.0V) Q, Q	330	600	900	330	600	900	330	650	900	ps

6. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 500 ohms to GND, C_L = 20 pF.
7. Reference (V_{CC} = 3.3V ± 5%; GND = 0V)
8. Skews are measured between outputs under identical conditions.

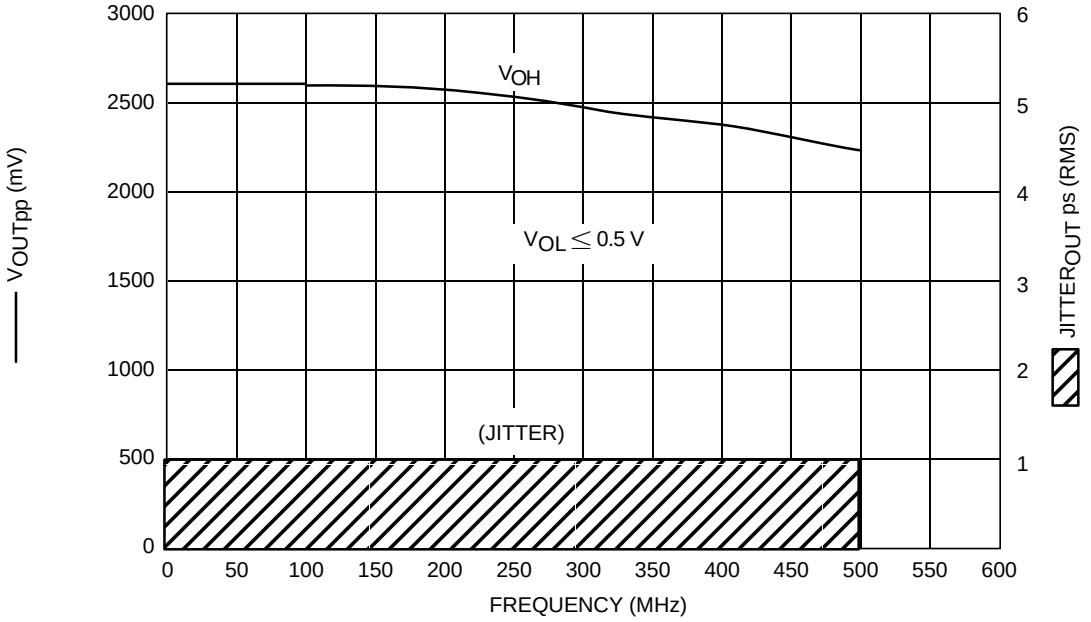
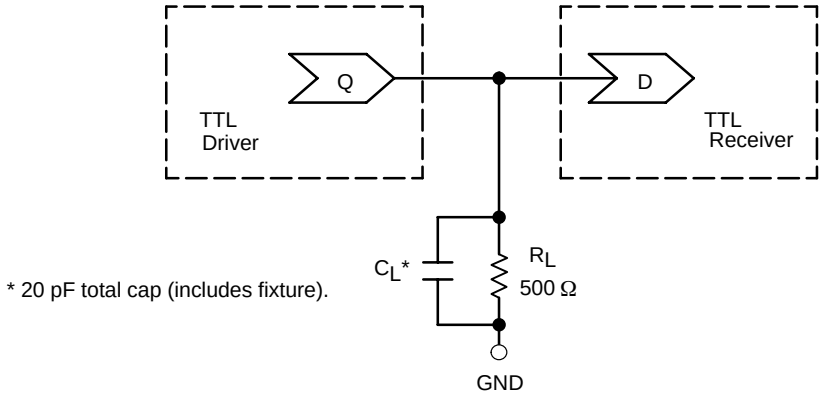


Figure 2. F_{max}/Jitter



* 20 pF total cap (includes fixture).

Figure 3. TTL Output Loading Used for Device Evaluation

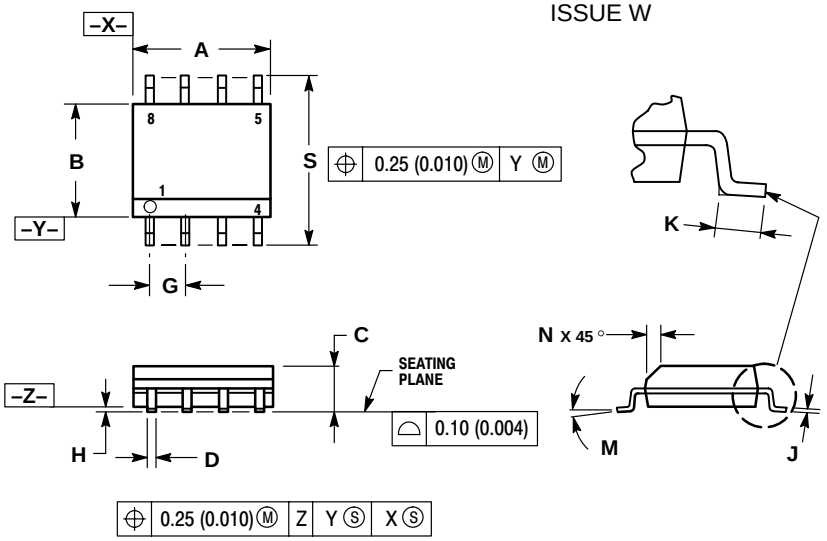
Resource Reference of Application Notes

AN1404	–	ECLinPS Circuit Performance at Non–Standard V_{IH} Levels
AN1405	–	ECL Clock Distribution Techniques
AN1406	–	Designing with PECL (ECL at +5.0 V)
AN1503	–	ECLinPS I/O SPICE Modeling Kit
AN1504	–	Metastability and the ECLinPS Family
AN1560	–	Low Voltage ECLinPS SPICE Modeling Kit
AN1568	–	Interfacing Between LVDS and ECL
AN1596	–	ECLinPS Lite Translator ELT Family SPICE I/O Model Kit
AN1650	–	Using Wire–OR Ties in ECLinPS Designs
AN1672	–	The ECL Translator Guide
AND8001	–	Odd Number Counters Design
AND8002	–	Marking and Date Codes
AND8020	–	Termination of ECL Logic Devices

For an updated list of Application Notes, please see our website at http://onsemi.com.

PACKAGE DIMENSIONS

SO–8
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751–07
ISSUE W

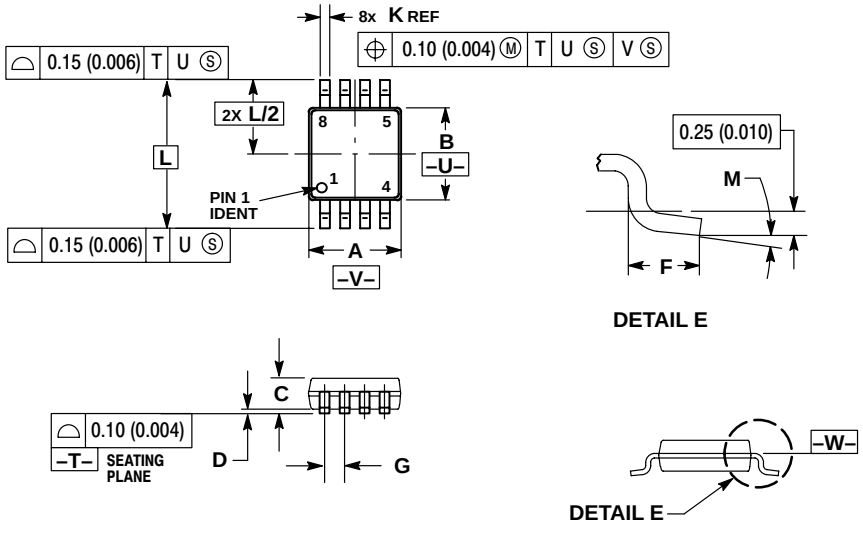


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

PACKAGE DIMENSIONS

TSSOP–8
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948R–02
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

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